

Description

The SIR401DP-T1-GE3 uses advanced trench technology to provide excellent R_{DS(ON)}, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

 $V_{DS} = -18V I_{D} = -80A$

 $R_{DS(ON)}$ <3 m Ω V_{GS}=-10V

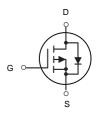
Application

Battery protection

Load switch

Uninterruptible power supply

DFN5X6-8L (PowerPAK-SO-8)



P-Channel MOSFET

Package Marking and Ordering Information

Product ID	Pack	Brand	Qty(PCS)
SIR401DP-T1-GE3	DFN5X6-8L (PowerPAK-SO-8)	HXY MOSFET	5000

Absolute Maximum Ratings (Tc=25 ℃ unless otherwise noted)

Symbol	Parameter	Rating	Units	
Vos	Drain-Source Voltage	-18	V	
Vgs	Gate-Source Voltage ±12		V	
I _D @Tc=25°C	Continuous Drain Current, V _{GS} @ 10V ¹	-80	А	
Ірм	Pulsed Drain Current ² -360		А	
P _D @T _C =25°C	Total Power Dissipation ⁴	ver Dissipation ⁴ 41.67		
Тѕтс	Storage Temperature Range	-55 to 150	°C	
TJ	Operating Junction Temperature Range -55 to 1		°C	
Reja	Thermal Resistance Junction-Ambient ¹	I Resistance Junction-Ambient ¹ 62		
Rejc	Reuc Thermal Resistance Junction-Case ¹		°C/W	



Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =-250uA	-18			V	
△BV _{DSS} /△T _J	BV _{DSS} Temperature Coefficient	Reference to 25°C , I _D =-1mA		-0.008		V/°C	
I _{DSS}	Drain-Source Leakage Current	V _{DS} =-20V , V _{GS} =0V , T _J =25°C			-1	uA	
	Diam-Source Leakage Current	V _{DS} =-16V , V _{GS} =0V , T _J =125°C			-30	uA	
Igss	Gate-Source Leakage Current	V _{GS} =±12V , V _{DS} =0V			±500	nA	
	Static Drain-Source On-Resistance						
R _{DS(ON)}		V _{GS} =-4.5V , I _D =-20A		2.5	3.0	mΩ	
		V _{GS} =-2.5V , I _D =-20A		3.3	4.5		
V _{GS(th)}	Gate Threshold Voltage)/ -\/	-0.4	-0.6	-1.0	V	
△Vgs	V _{GS(th)} Temperature Coefficient	$V_{GS}=V_{DS}$, $I_D=-250uA$		-3.44		mV/°C	
gfs	Forward Transconductance	V _{DS} =-10V , I _S =-3A		30		S	
Qg	Total Gate Charge ^{2,3}			149	225		
Q _{gs}	Gate-Source Charge ^{2,3}	V _{DS} =-16V , V _{GS} =-4.5V , I _D =-5A		14.4	22	nC	
Q_{gd}	Gate-Drain Charge ^{2, 3}			42.8	65		
T _{d(on)}	Turn-On Delay Time ^{2,3}			21.2	42		
Tr	Rise Time ^{2, 3}	V_{DD} =-15V , V_{GS} =-4.5V , R_{G} =25 Ω		20.6	40	nS	
$T_{d(off)}$	Turn-Off Delay Time ^{2,3}	I _D =-1A		26	52		
T _f	Fall Time ^{2, 3}			400	600		
Ciss	Input Capacitance			12000	16000		
Coss	Output Capacitance	V_{DS} =-15V , V_{GS} =0V , F=1MHz		1670	2500	pF	
Crss	Reverse Transfer Capacitance			730	1100		
Rg	Gate resistance	V _{GS} =0V, V _{DS} =0V, F=1MHz		2.6		Ω	
Is	Continuous Source Current	\\ -\\ -0\\ Faras O:+			-85	Α	
Ism	Pulsed Source Current	V _G =V _D =0V , Force Current			-190	Α	
V _{SD}	Diode Forward Voltage	V _{GS} =0V , I _S =-1A , T _J =25°C			-1	V	

Note:

- 1. Repetitive Rating: Pulsed width limited by maximum junction temperature.
- 2. The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%.
- Essentially independent of operating temperature.

Typical Performance Characteristics

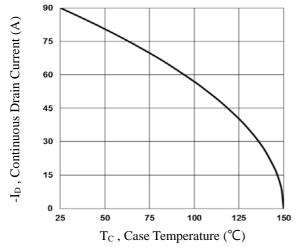


Fig.1 Continuous Drain Current vs. Tc

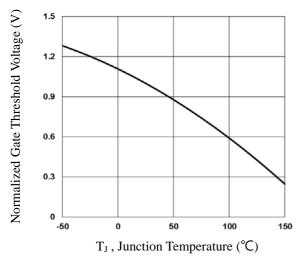


Fig.3 Normalized V_{th} vs. T_J

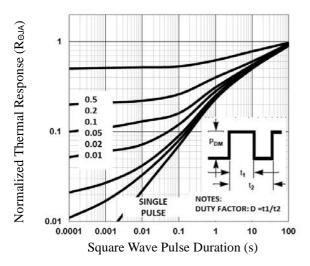


Fig.5 Normalized Transient Response

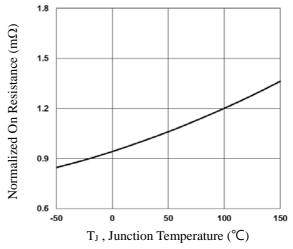


Fig. 2 Normalized RDSON vs. TJ

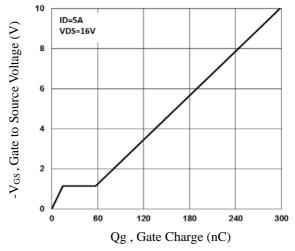


Fig.4 Gate Charge Waveform

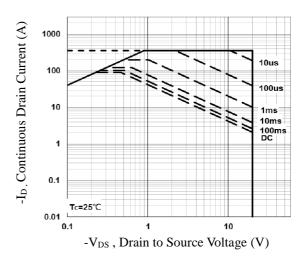
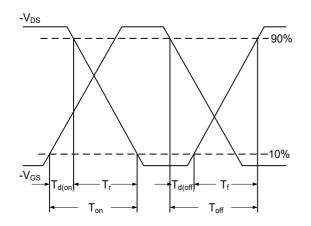
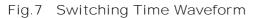


Fig.6 Maximum Safe Operation Area





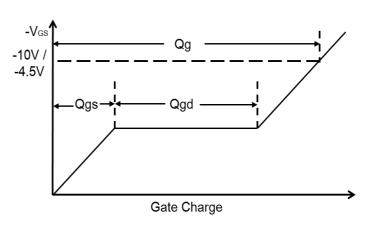
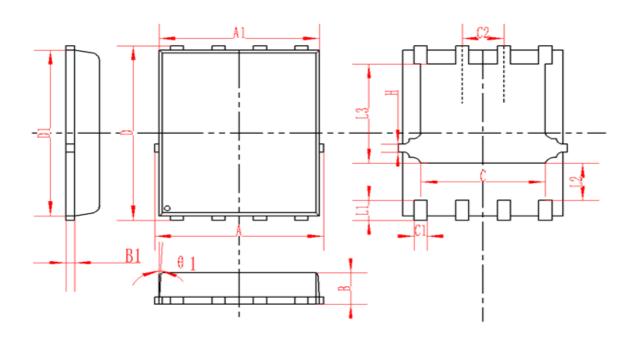


Fig.8 Gate Charge Waveform

DFN3X3-8L(PowerPAK-SO-8) Package Information



SYMBOL	MM		INCH				
	MIN	NOM	MAX	MIN	NOM	MAX	
А	4.95	5	5.05	0.195	0.197	0.199	
A1	4.82	4.9	4.98	0.190	0.193	0.196	
D	5.98	6	6.02	0.235	0.236	0.237	
D1	5.67	5.75	5.83	0.223	0.226	0.230	
В	0.9	0.95	1	0.035	0.037	0.039	
B1	0.254REF		0.010REF				
С	3.95	4	4.05	0.156	0.157	0.159	
C1	0.35	0.4	0.45	0.014	0.016	0.018	
C2		1.27TYP			0.5TYP		
θ1	8°	10°	12°	8°	10°	12°	
L1	0.63	0.64	0.65	0.025	0.025	0.026	
L2	1.2	1.3	1.4	0.047	0.051	0.055	
L3	3.415	3.42	3.425	0.134	0.135	0.135	
Н	0.24	0.25	0.26	0.009	0.010	0.010	



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